Taiwan Semiconductor

# 6A, 200V - 600V Ultra Fast Surface Mount Rectifier

### FEATURES

- AEC-Q101 qualified
- Very low profile, typical height of 1.1mm
- Excellent high temperature stability
- Glass passivated chip junction
- Controlled avalanche characteristics
- Low leakage current
- High forward surge capability
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

## APPLICATIONS

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

## **MECHANICAL DATA**

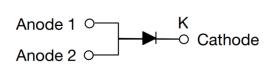
- Case: TO-277A (SMPC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.095g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	6	А	
V <sub>RRM</sub>	200 - 600	V	
I <sub>FSM</sub>	80	А	
T <sub>J MAX</sub>	175	°C	
Package	TO-277A (SMPC)		
Configuration	Single die		





TO-277A (SMPC)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	TPUH6DH	TPUH6JH	UNIT
Marking code on the device		UH6D	UH6J	
Repetitive peak reverse voltage	V <sub>RRM</sub>	200	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	420	V
Forward current	I <sub>F</sub>	(	6	А
Surge peak forward current 8.3ms single half sine wave superimposed on rated load	I <sub>FSM</sub>	8	0	А
Junction temperature	TJ	-55 to	+175	°C
Storage temperature	T <sub>STG</sub>	-55 to	+175	°C



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ТҮР	UNIT	
Junction-to-lead thermal resistance <sup>(1)</sup>	R <sub>θJL</sub>	12	°C/W	
Junction-to-ambient thermal resistance <sup>(2)</sup>	R <sub>eJA</sub>	80	°C/W	

Notes:

- 1. Mounted on FR4 PCB with 16mm x 16mm Cu pad area
- 2. Free air, mounted on recommended pad

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
	TPUH6DH	I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C		0.80	-	V
	TPUH6JH			1.98	-	V
	TPUH6DH	L 0.4 T 0500		0.87	1.05	V
Ferward valtage <sup>(1)</sup>	TPUH6JH	I <sub>F</sub> = 6A, T <sub>J</sub> = 25°C		2.45	3.00	V
Forward voltage <sup>(1)</sup>	TPUH6DH	I <sub>F</sub> = 3A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.65	-	V
	TPUH6JH			1.23	-	V
	TPUH6DH	I <sub>F</sub> = 6A, T <sub>J</sub> = 125°C		0.73	0.90	V
	TPUH6JH			1.59	1.80	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		$T_J = 25^{\circ}C$	I <sub>R</sub>	-	10	μA
		T <sub>J</sub> = 125°C		-	200	μA
Junction capacitance		1MHz, V <sub>R</sub> = 4.0V	CJ	50	-	pF
Reverse recovery time		IF = 0.5A, IR = 1.0A Irr = 0.25A	t <sub>rr</sub>	-	25	ns
		$I_F = 1A$ , di/dt = -50A/µs $V_R = 30V$	t <sub>rr</sub>	-	45	ns

#### Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

## ORDERING INFORMATION

ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
TPUH6xH	TO-277A (SMPC)	6,000 / Tape & Reel

Notes:

1. "x" defines voltage from 200V(TPUH6DH) to 600V(TPUH6JH)



### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

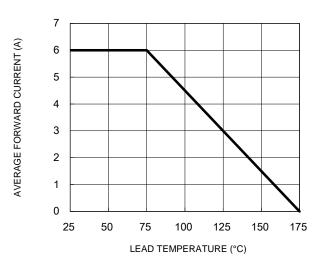
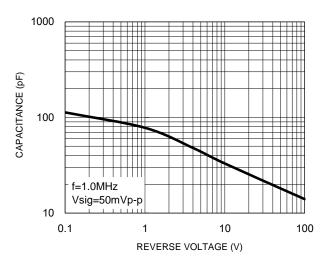


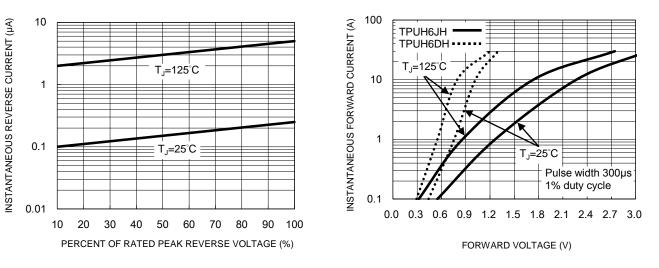
Fig.1 Forward Current Derating Curve

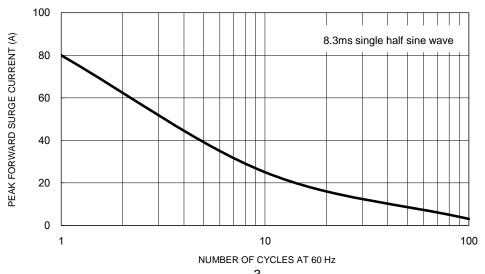
#### **Fig.3 Typical Reverse Characteristics**



#### **Fig.2 Typical Junction Capacitance**

**Fig.4 Typical Forward Characteristics** 



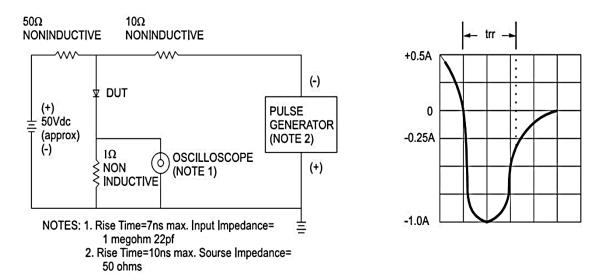


## Fig.5 Maximum Non-Repetitive Forward Surge Current



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

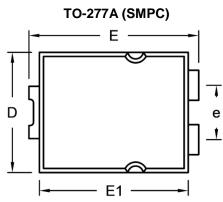


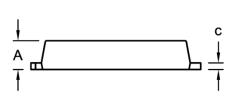
#### Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

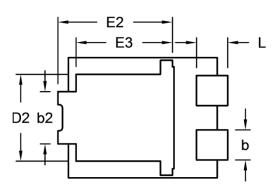
# TPUH6DH – TPUH6JH

Taiwan Semiconductor



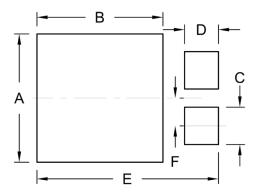




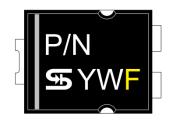


DIM.	Unit (mm)		Unit (	(inch)
	Min.	Max.	Min.	Max.
A	1.000	1.200	0.039	0.047
b	1.000	1.300	0.039	0.051
b2	1.850	2.150	0.073	0.085
с	0.175	0.325	0.007	0.013
D	4.550	4.650	0.179	0.183
D2	3.170	3.470	0.125	0.137
E	6.350	6.650	0.250	0.262
E1	5.650	5.750	0.222	0.226
E2	4.235	4.535	0.167	0.179
E3	3.540	3.840	0.139	0.151
е	1.930	2.230	0.076	0.088
L	1.043	1.343	0.041	0.053

SUGGESTED PAD LAYOUT



**MARKING DIAGRAM** 



Symbol	Unit (mm)	Unit (inch)
А	4.80	0.189
В	4.72	0.186
С	1.40	0.055
D	1.27	0.050
E	6.80	0.268
F	1.04	0.041

P/N = Marking Code

YW = Date Code

F = Factory Code



Taiwan Semiconductor

## Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.